16th International

Mechatronic Integration Discourse

Amberg Congress Centrum, Germany, 2nd – 3rd July 2025

2nd Call for Papers

The Internet of Things (IoT) leads to an ongoing change of our life: Laptops, tablets and smart phones translate spoken texts simultaneously in any language, answer semantical questions and support our daily life. Cars drive autonomously, use current traffic intelligence to avoid congestions and warn others instantly in case of any danger. Every object in the future factories is able to exchange data, work pieces may choose discretely their optimal process route and machines report maintenance issues betimes. And last but not least wearable electronic accompany us in watches to control our vital functions, in shoes to detect our pace and in glasses to display essential information.

All these kinds of innovative gimmicks applied in Cyber Physical Systems integrate sensory functions, electronic intelligence, energy storages, harvesting and communication capabilities in tightest installation spaces on freely formed surfaces and in light plastic housings. All of them use antennas, which have to be designed spatially to boost their emitting performance. More and more, there will neither be enough space for flat circuit boards, nor for other electromechanical parts.

Mechatronics integration extends from the chip level as MEMS, through packaging, assemblies and products, to the system level. In doing so, mechatronics integrates all physical areas: mechanics, electrics, electronics, thermics, magnetics, optics, computer science. For this purpose, there are of course not only planar build-up technologies, but also always spatial solutions. In addition, structuring, metallization or printing processes must continue to be developed dynamically in order to apply mechatronic functions to any materials such as ceramics, fabrics, foils, paper/cardboard and even skin.

organized by
Research Association
3-D MID e.V.

in cooperation with
University of Erlangen-Nuremberg
Institute for Factory Automation
and Production Systems – FAPS

Submission of Abstracts and Papers

Experts of industry and science (IEEE explore) are invited to present a paper on the topics shown in the figure on the next page. For this, abstracts in the extent of max. 500 words have to be provided via the online conference tool including the following details:

- Title of the paper
- Preferred classification (Industrial or scientific track)
- Allocation to field of topic
- Name and address of the author(s)

Further information and a template for your abstract is available at the congress pages on:

www.3d-mid.de/en/mid-congress/

Please note the dates stated below. Abstracts will be verified before acceptance by the program committee. All accepted contributions will be published in the congress proceedings. Information regarding the presentations will be sent separately. Speakers will be granted discounted participation fees.

Important Dates

Submission of abstracts	February 10th, 2025
Acceptance of abstracts	February 25th, 2025
Submission of scientific full papers	March 18th, 2025
Feedback on full papers	April, 09th, 2025
Final submission	May 4th, 2025
Mechatronic Integration Discourse	July 2nd-3rd, 2025
Technical Tour	July 3rd, 2025

Congress fees (plus VAT)

	Regular	Early bird*
Standard fee	€ 1.180,-	€ 980,-
Reduced fee**	€ 880,-	€ 680,-

**registration before February 25th 2025*
***for members of 3-D MID e.V. and speakers*

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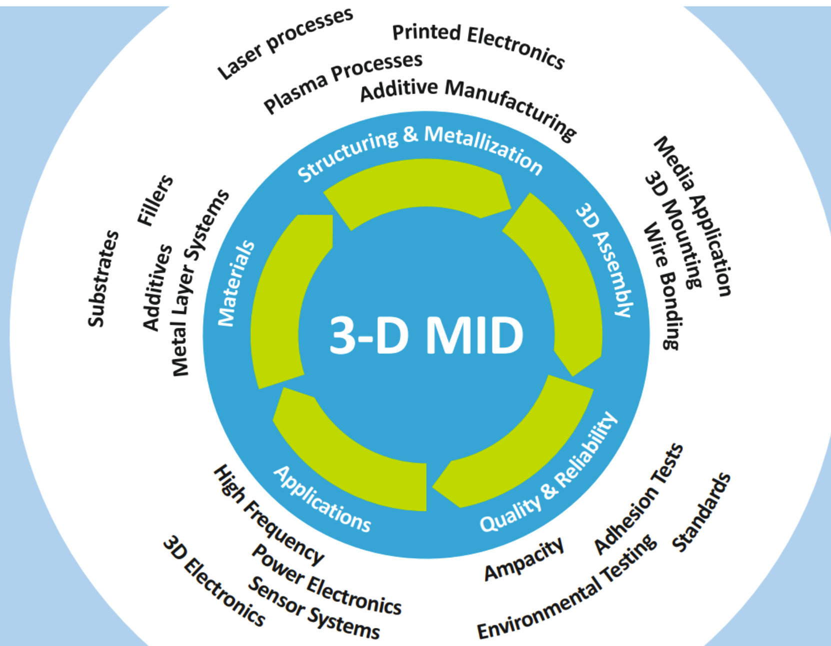

General Information

Congress Location: The congress will take place at the Amberg Congress Centrum in Amberg (ACC) in Northern Bavaria. The airport of Nuremberg is within an hour's driving distance by car or train.

Conference Language: The conference language is English.

Research Market: All our current research projects funded by the German Federal Ministry for Economic Affairs and Climate Action (BMWK) and supervised by the IGF/DLR will present their findings in a poster session.

Exhibition: The event will be complemented by an accompanying industrial exhibition with booths, table-top-presentations and posters. Further information is available at www.3dmid.de

Invited Keynotes: Distinguished scientists and industrial experts will present groundbreaking discoveries and latest serial applications in MID technology.

The **MID Award 2025** will be granted for outstanding investigation in the field of MID technology by 3-D MID e.V.

Best Paper Award: 3-D MID e.V. honors the best paper and the best presentation with a Best Paper and a Best Presentation Award.

Technical Tour: On Thursday July 3rd, 2025 a tour will be offered.

Further Information: For further information visit our website www.3dmid.de or directly contact the 3-D MID e.V. office.

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